

650V N-CHANNEL POWER MOSFET

GENERAL DESCRIPTION

The Power MOSFET is fabricated using advanced super junction technology. The resulting device has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency.

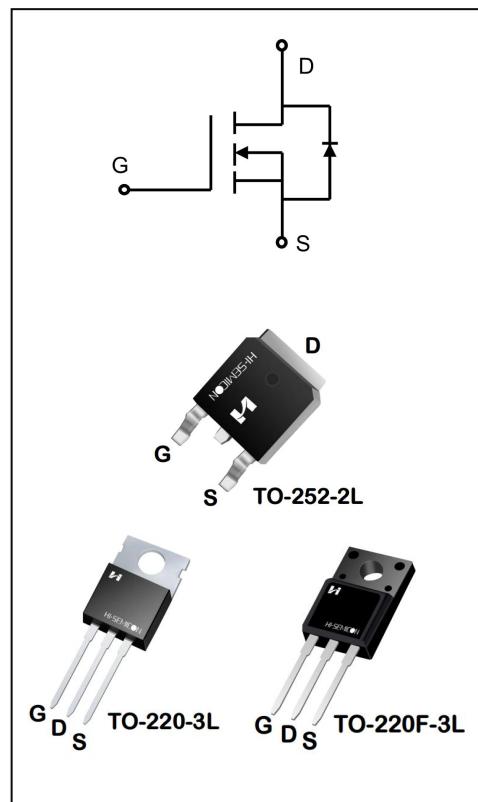
Features

- ◆ $V_{DS}=650V$, $I_D=8A$
- ◆ $V_{DS,min@T_f(max)}=700V$
- ◆ $R_{DS(ON)}$

TYP: $520m\Omega @ V_{GS}=10V$, $I_D=4A$

Applications

- ◆ Power factor correction (PFC)
- ◆ Switched mode power supplies (SMPS)
- ◆ Uninterruptible power supply (UPS)
- ◆ LED lighting power



ORDERING INFORMATION

Part No.	Package	Marking	Material	Packing
SCF65R540T	TO-220F-3L	SCF65R540T	Pb free	Tube
SCP65R540T	TO-220-3L	SCP65R540T	Pb free	Tube
SCD65R540T	TO-252-2L	SCD65R540T	Pb free	Reel

ABSOLUTE MAXIMUM RATINGS (T_J=25°C unless otherwise noted)

Characteristics	Symbol	Ratings			Unit
		SCF65R540T	SCD65R540T	SCP65R540T	
Drain-Source Voltage	V _{DS}	650			V
Gate-Source Voltage	V _{GS}	±30			V
Drain Current	I _D	8			A
T _C = 100°C		5.6			
Drain Current Pulsed(Note 1)	I _{DM}	30			A
Power Dissipation(T _C =25°C) -Derate above 25°C	P _D	35	48	85	W
		0.28	0.38	1.2	W/°C
Single Pulsed Avalanche Energy (Note 2)	E _{AS}	89			mJ
Operation Junction Temperature Range	T _J	-55~+150			°C
Storage Temperature Range	T _{stg}	-55~+150			°C
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	TL	300			°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	MAX			Unit
		SCF65R540T	SCD65R540T	SCP65R540T	
Thermal Resistance, Junction-to-Case	R _{θJC}	3.57	2.6	2.1	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	62.5	62.0	65.0	°C/W

ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain -Source Breakdown Voltage	B _{VDSS}	V _{GS} =0V, I _D =250μA	650	700	--	V
		V _{GS} =0V, I _D =250μA, T _j =150	700	--	--	
Drain-Source Leakage Current	I _{DSS}	V _{DS} =650V, V _{GS} =0V	--	--	1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =30V, V _{DS} =0V	--	--	100	nA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =-30V, V _{DS} =0V	--	--	-100	
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D =250μA	2	3.1	4.0	V
Static Drain- Source On State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =4A	--	520	580	mΩ
Dynamic Characteristics						
Gate Resistance	R _g	V _{GS} =0V; f=1.0MHZ	1	3.1	10	Ω
Input Capacitance	C _{iss}	V _{DS} =100V V _{GS} =0V f=1.0MHZ	--	479	--	pF
Output Capacitance	C _{oss}		--	20.6	--	
Reverse Transfer Capacitance	C _{rss}		--	2.5	--	

Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=325V, V_{GS}=10V$ $R_G=25\Omega, I_D=8A$ (Note 3.4)	--	11.5	--	ns
Turn-on Rise Time	t_r		--	32.6	--	
Turn-off Delay Time	$t_{d(off)}$		--	52.1	--	
Turn-off Fall Time	t_f		--	26.5	--	
Total Gate Charge	Q_g	$V_{DS}=520V, I_D=8A$ $V_{GS}=10V$ (Note 3.4)	--	18	--	nC
Gate-Source Charge	Q_{gs}		--	4.2	--	
Gate-Drain Charge	Q_{gd}		--	9.2	--	

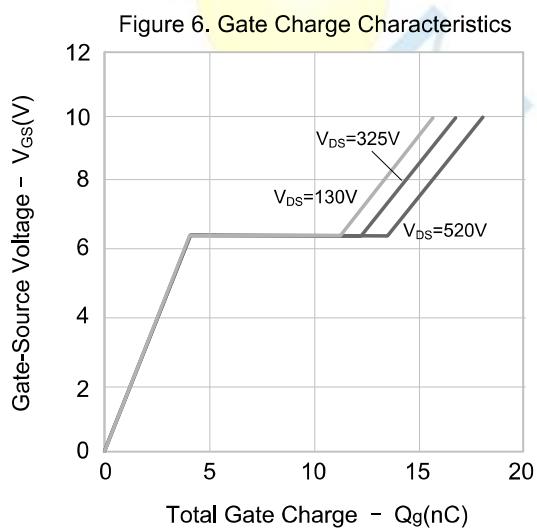
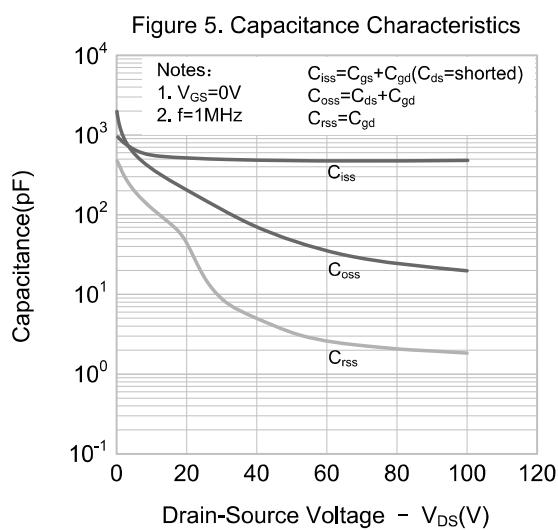
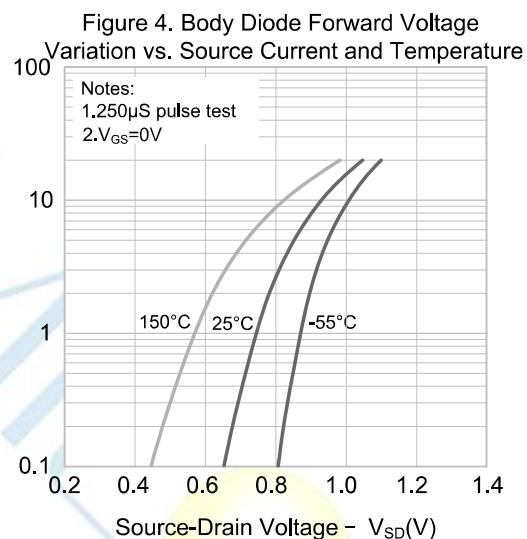
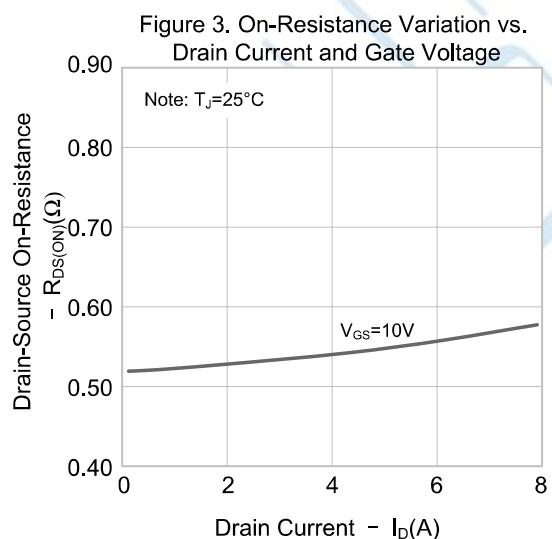
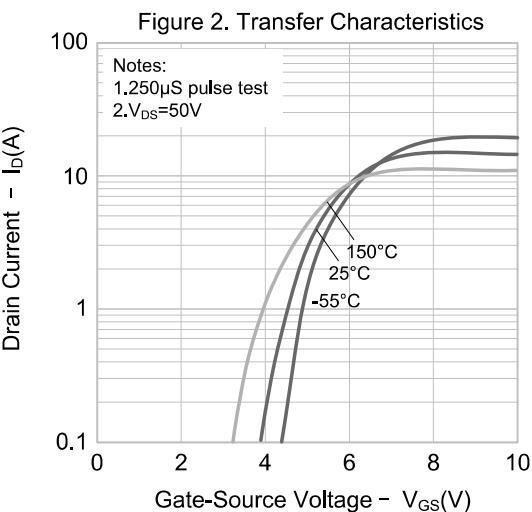
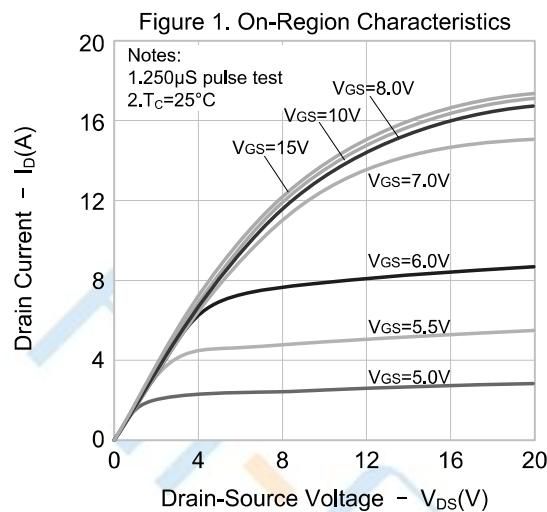
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	Integral Reverse P-N Junction Diode in the MOSFET	--	--	8	A
Pulsed Source Current	I_{SM}		--	--	32	
Diode Forward Voltage	V_{SD}	$I_S=8A, V_{GS}=0V$	--	0.9	1.4	V
Reverse Recovery Time	T_{rr}	$I=8A, V_{GS}=0V,$ $dI/dt=100A/\mu s$ (Note 3)	--	411	--	ns
Reverse Recovery Charge	Q_{rr}		--	12	--	nC

NOTE:

1. Pulse width limited by maximum junction temperature
2. L=79mH, $V_{DD}=100V$, $V_G=10V$, $R_G=25\Omega$, starting $T_J=25^\circ C$
3. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$
4. Essentially independent of operating temperature

Typical Performance Characteristics



Typical Performance Characteristics

Figure 7. Breakdown Voltage Variation vs. Temperature

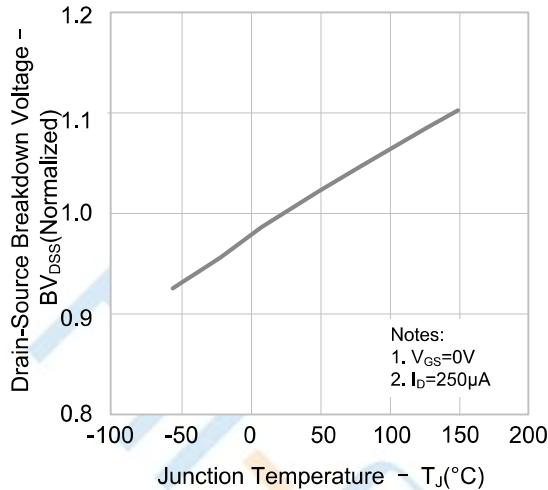


Figure 8. On-resistance Variation vs. Temperature

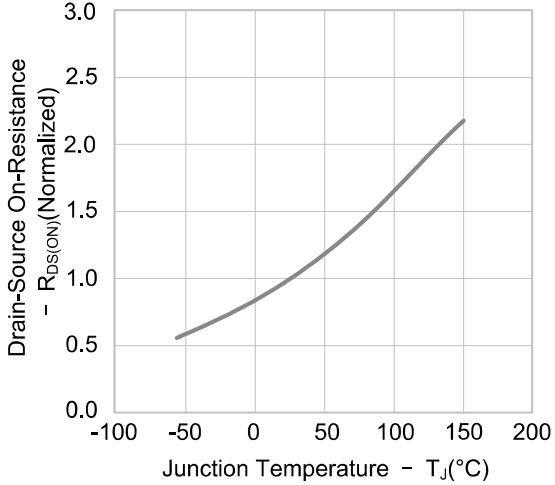
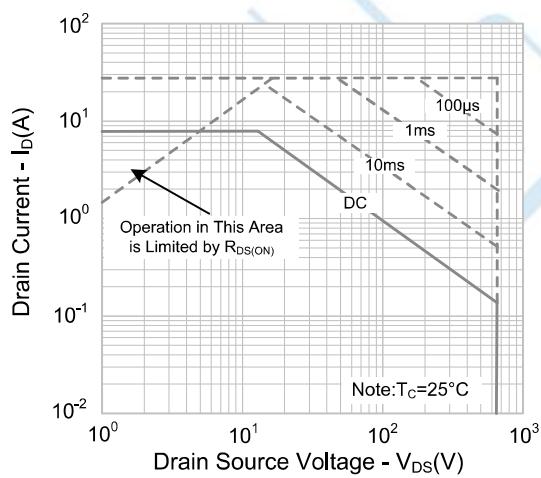
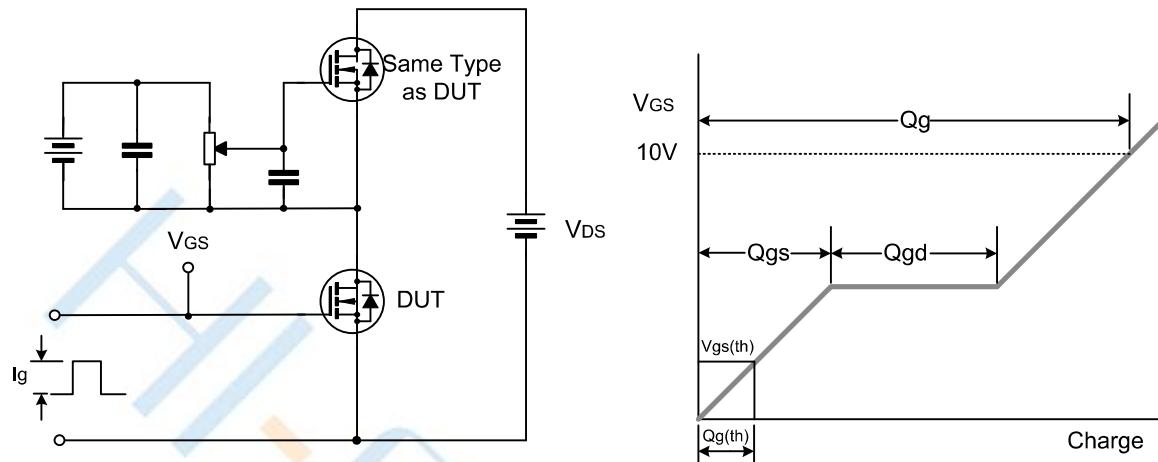


Figure 9-1. Max. Safe Operating Area

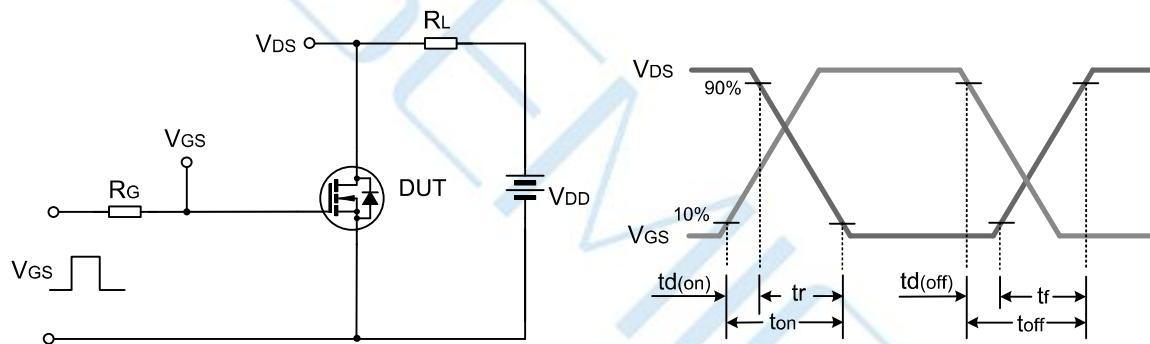


Test Circuit

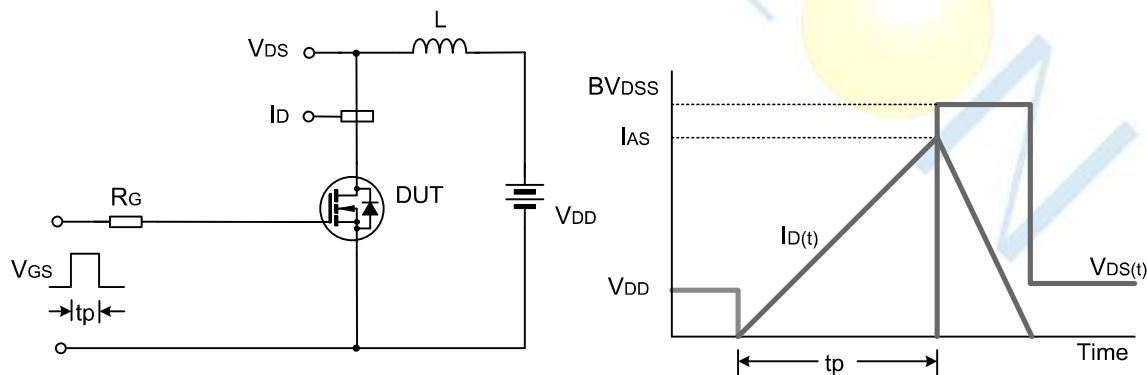
Gate Charge Test Circuit & Waveform



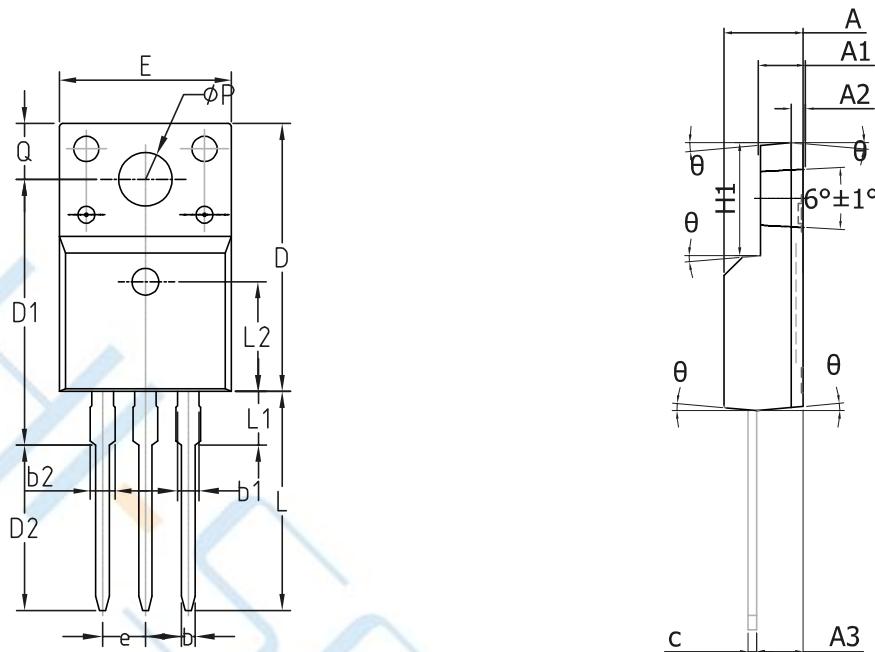
Resistive Switching Test Circuit & Waveform



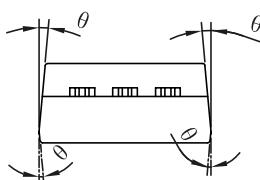
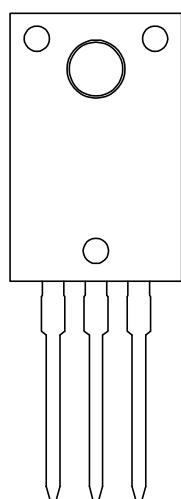
Unclamped Inductive Switching Test Circuit & Waveform



Package Dimensions of TO-220F-3L

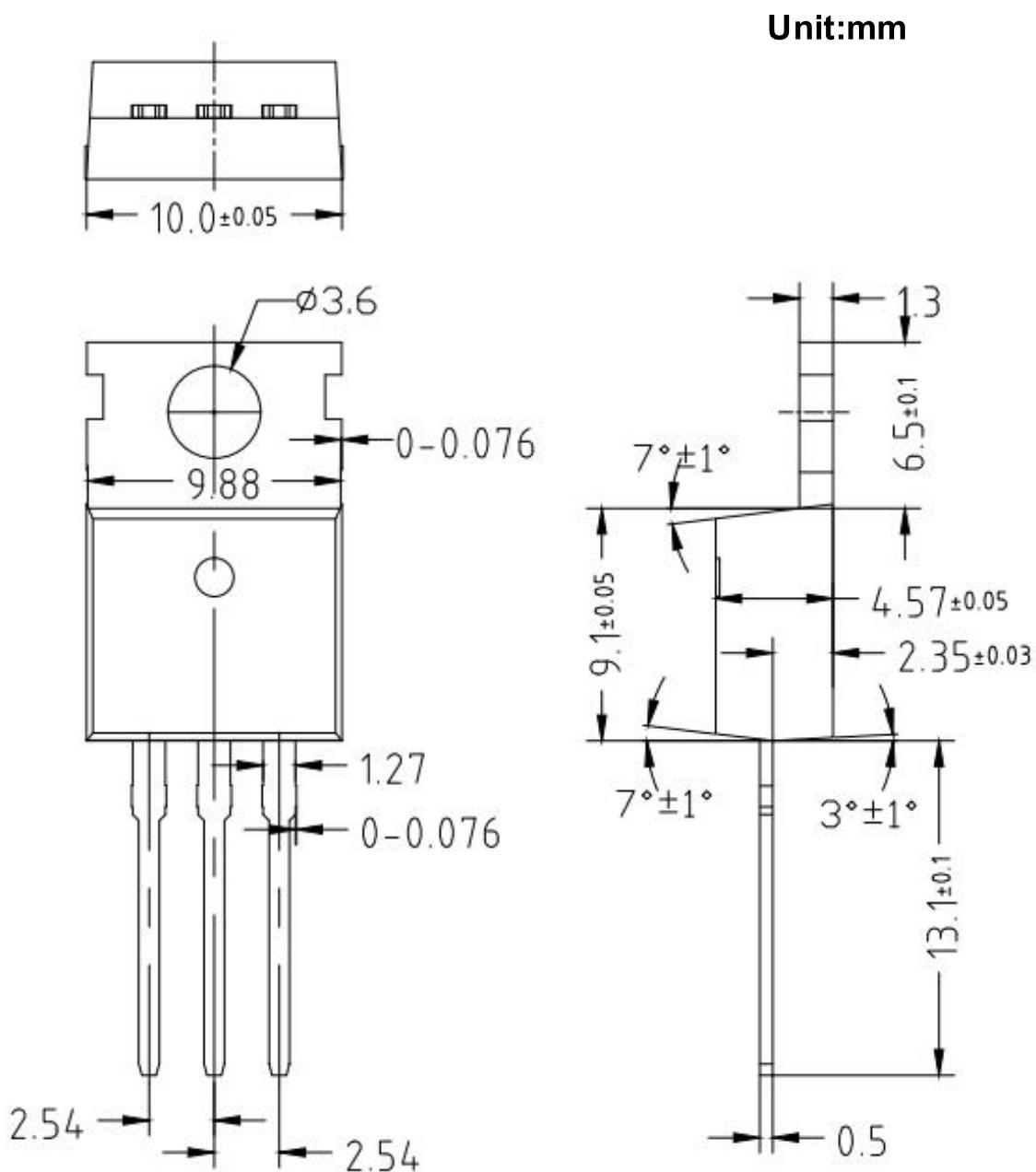


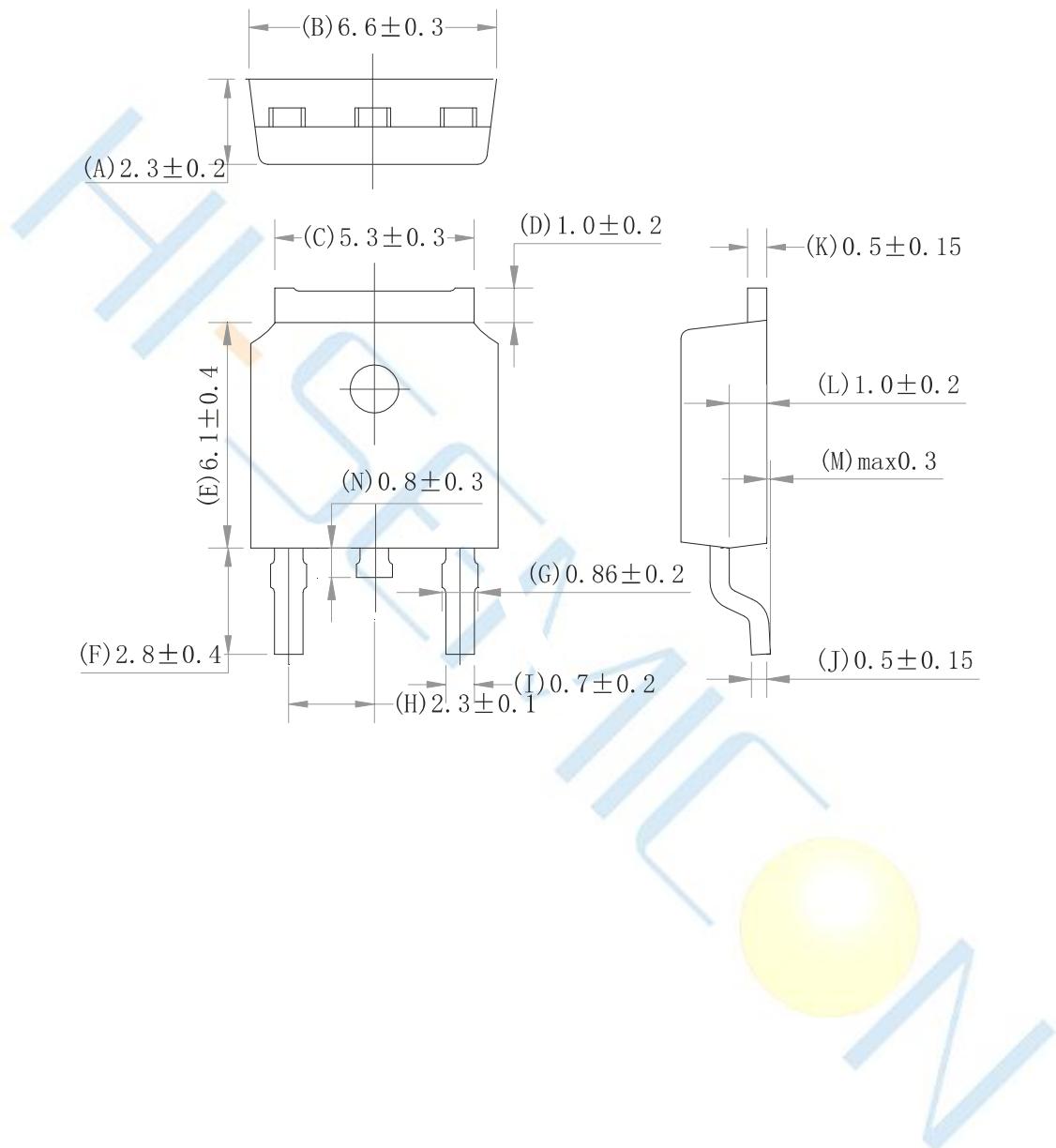
COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)



SYMBOL	MIN	NOM	MAX
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A2		0.70 REF	
A3	2.56	2.76	2.96
b	0.70	0.80	0.90
b1	1.17	1.2	1.25
b2	1.17	1.2	1.25
c	0.45	0.50	0.60
D	15.67	15.87	16.07
D1	15.55	15.75	15.95
D2	10.0	10.2	10.4
E	9.96	10.16	10.36
e	2.54BSC		
H1	6.48	6.68	6.88
L	12.68	12.98	13.28
L1	-	-	3.50
L2	6.50REF		
φP	3.08	3.18	3.28
Q	3.20	3.30	3.40
θ 1	1°	3°	5°
A4	0.53	0.56	0.59

Package Dimensions of TO-220-3L



Package Dimensions of TO-252-2L

Disclaimer:

- Hi-semicon reserves the right to make changes to the information herein for the improvement of the design and performance without further notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
- All semiconductor products malfunction or fail with some probability under special conditions. When using Hi-semicon products in system design or complete machine manufacturing, it is the responsibility of the buyer to comply with the safety standards strictly and take essential measures to avoid situations in which a malfunction or failure of such Hi-semicon products could cause loss of body injury or damage to property.
- Hi-semicon will supply the best possible product for customers!

